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		US 20040239438	20041202	18		333/24R	333/109	Benham, John R. et al.	R C C (
		US 20040197955	20041007	26	Methods for assembly and packaging of flip chip	438/108	438/126	Lee, Teck Kheng	R T D I	r n n
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	ר	US 20040159957	20040819	32	Interposer substrate and wafer scale interposer	257/778	257/E21.503; 257/E23.004	Lee, Teck Kheng	k L L I	- r r
	c c	US 20040137659	20040715	16	[METHOD OF FABRICATING A SOLDER	438/106		Ding, Yi-Chuan et al.	8 E E I	n c
	o c	US 20040104463	20040603	:16 :	Crack resistant interconnect module	257/686	257/E23.062; 257/E23.069;	Gorrell, Robin E. et al.	e n n	a n c
	ព ព	US 20030166312	20030904	27	Methods for assembly and packaging of flip chip	438/107	257/E23.004; 257/E23.067;	Lee, Teck Kheng	R C C	. r. c
	n n	US 20030164548	20030904	29	Flip chip packaging using recessed interposer terminals	257/738	257/678; 257/737;	Lee, Teck Kheng	k u u	n n c
	ה ה	US 20030164541	20030904	34	Method and apparatus for dielectric filling of flip chip	257/686	257/E21.503; 257/E23.004	Lee, Teck Kheng	P C C	a la c
	r r	US	20030102	9	Direct imaging process for forming resist pattern on a	430/325	430/302; 430/346;	Grunwald, John J. et al	ו יו יו ק	n n
	r r	US 20010041389	20011115	14	Smiconductor device having a thermoset- containing	438/118		Farquhar, Donald S. et al.	ף ר ר ו	ה ה
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	m n	US 6534160 B2	20030318	13	Semiconductor device having a thermoset-containing	428/209	174/258; 174/259;	Farquhar; Donald S. et	E C C I	c c r

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8	<u>:</u>	US 4954185 A		7	Method of applying adherent coating on copper	148/282	148/269; 148/272;	Kohm; Thomas S.	P.	Г	L l	- r	: [[
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